GENERAL DESCRIPTION

The bw1217x is a CMOS 10-bit A/D converter for video applications. It is a three-step pipelined A/D converter which consists of sample & hold, two multiplying DACs, and three 4-bit flash ADCs.

The maximum conversion rate of bw1217x is 30MSPS and supply voltage is 3.3V single.

TYPICAL APPLICATIONS

— PC or computer based video signal processing such as multi-media, scanner, etc.

— General Purpose video applications including camcorder, digital video, broad-casting and studio equipments.

— Medical electronics such as digital scope, transit recorder, radar.

FEATURES

— Resolution: 10Bit

— Differential Linearity Error: ±1.0 LSB

— Integral Linearity Error: ±2.0 LSB

— Maximum Conversion Rate: 30MSPS

— Sample & Hold Function Implemented

— Low Power Consumption: 82.5mW(Typ)

— Power Supply: 3.3V Single

— Operation Temperature Range: 0°C~70°C

FUNCTIONAL BLOCK DIAGRAM

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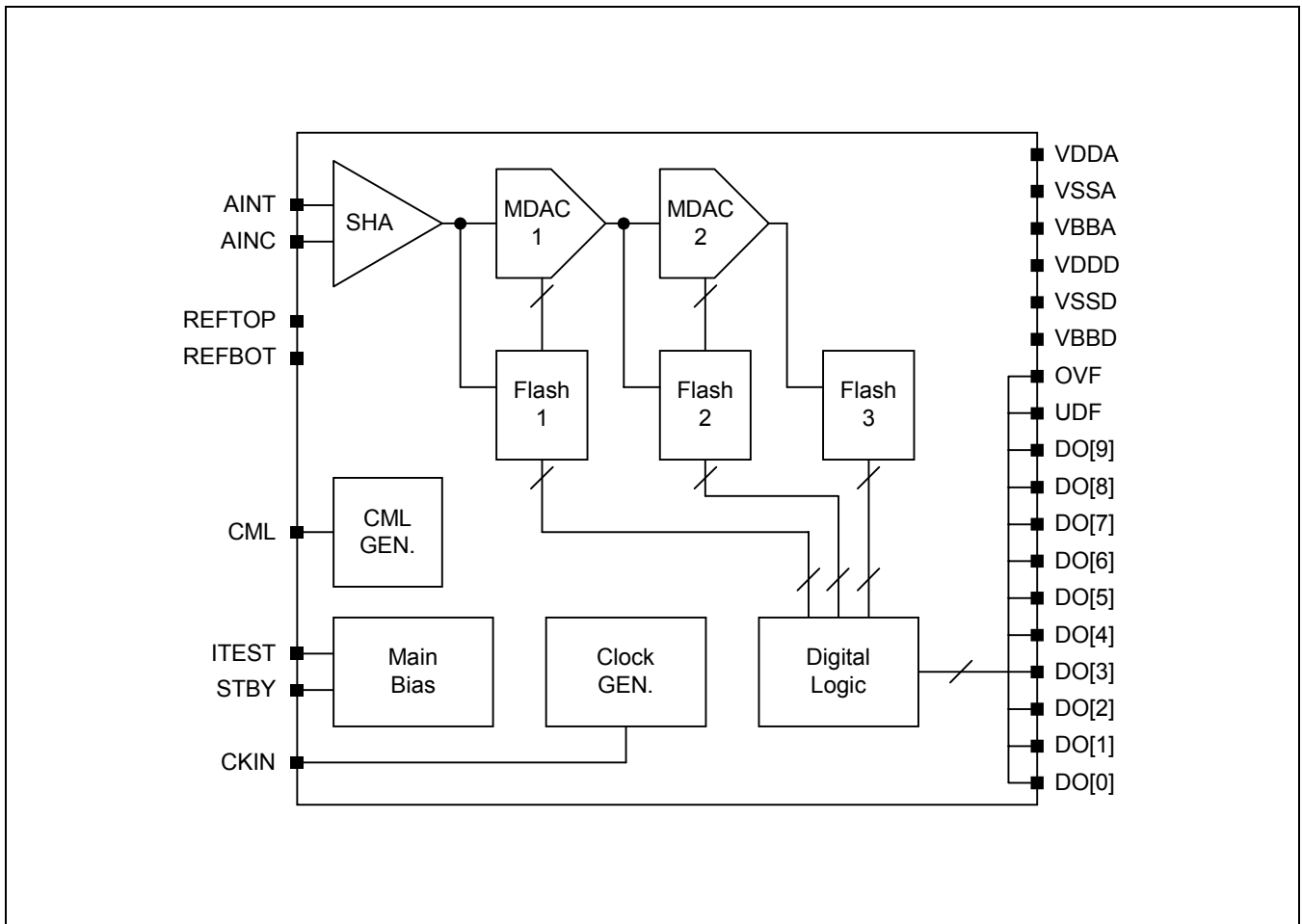
CORE PIN DESCRIPTION

Name	I/O Type	I/O PAD	Pin Description
AINT	AI	piar50_bb	Analog Input + Input Range: 1.9V ~ 1.4V
AINC	AI	piar50_bb	Analog Input – Input Range: 1.4V ~ 1.9V
REFMID	AB	pia_bb	Reference Mid Point (Test Pin)
REFTOP	AI	pia_bb	Reference Top (1.9V)
REFBOT	AI	pia_bb	Reference Bottom(1.4V)
VDDA	AP	vdda	Analog Power (3.3V)
VSSA	AG	vssa	Analog Ground
VBBA	AG	vbba	Analog Sub Bias
ITEST	AB	pia_bb	open = use internal bias point
STBY	DI	picc_bb	high = power saving standby mode (normally = gnd)
CKIN	DI	picc_bb	Sampling Clock Input
CML	AB	pia_bb	Internal Bias Point (Test Pin)
DO[9:0]	DO	pot2_bb	Digital Output
OVF	DO	pot2_bb	Overflow
UDF	DO	pot2_bb	Underflow
VBBD	DG	vbba	Digital Sub Bias
VSSD	DG	vssd	Digital Ground
VDDD	DP	vddd	Digital Power

I/O Type Abbr.

— AI: Analog Input

— DI: Digital Input

— AO: Analog Output

— DO: Digital Output

— AB: Analog Bidirectional

— DB: Digital Bidirectional

— AP: Analog Power

— DP: Digital Power

— AG: Analog Ground

— DG: Digital Ground

CODE CONFIGURATION
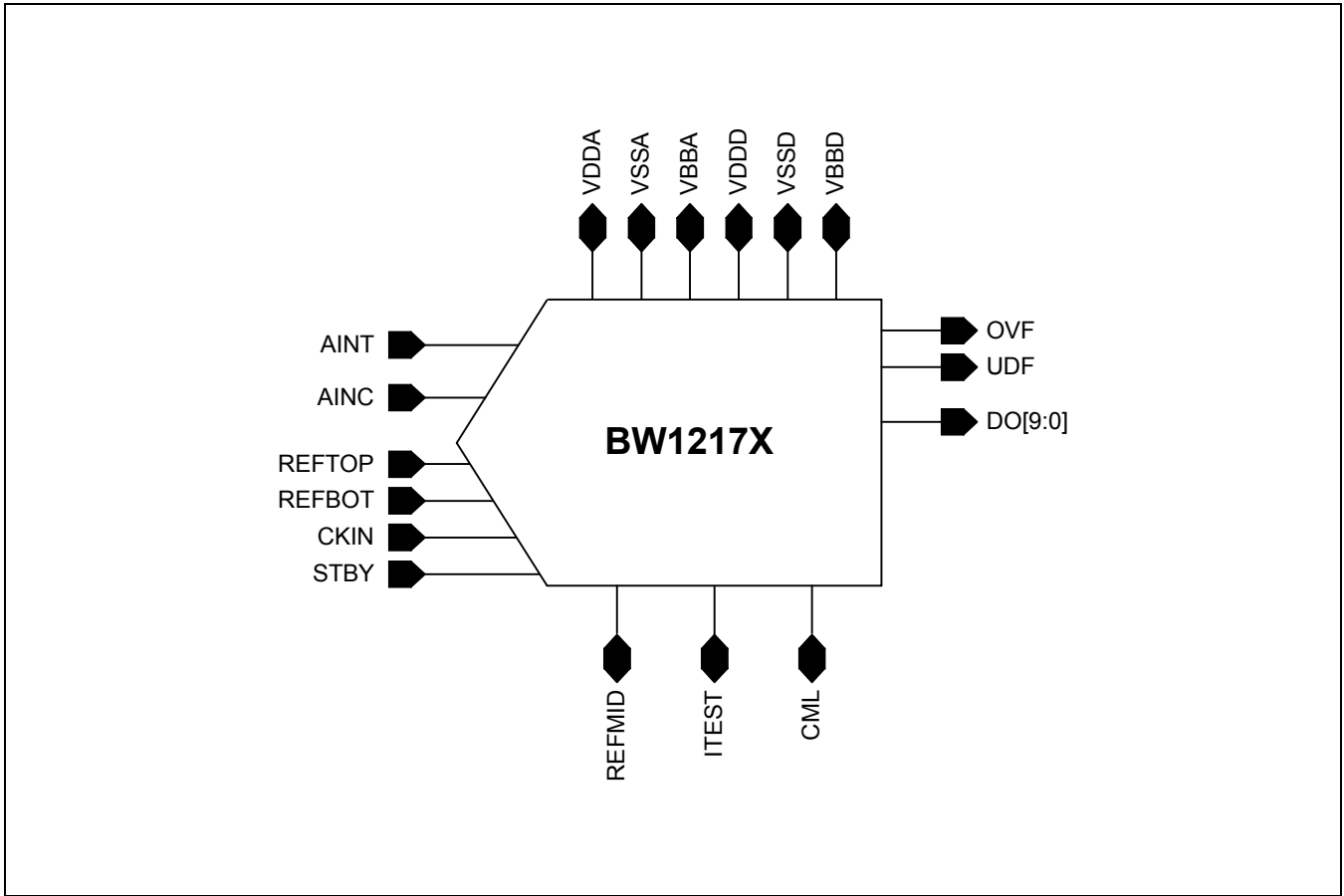
ABSOLUTE MAXIMUM RATINGS

Characteristic	Symbol	Value	Unit
Supply Voltage	VDD	4.5	V
Analog Input Voltage	AIN	VSS to VDD	V
Digital Input Voltage	CLK	VSS to VDD	V
Digital Output Voltage	$V_{OH},\ V_{OL}$	VSS to VDD	V
Storage Temperature Range	Tstg	-45 to 125	°C

NOTES:
1. ABSOLUTE MAXIMUM RATING specifies the values beyond which the device may be damaged permanently. Exposure to ABSOLUTE MAXIMUM RATING conditions for extended periods may affect reliability. Each condition value is applied with the other values kept within the following operating conditions and function operation under any of these conditions is not implied.
2. All voltages are measured with respect to VSS unless otherwise specified.
3. 100pF capacitor is discharged through a 1.5KΩ resistor (Human body model)

RECOMMENDED OPERATING CONDITIONS

Characteristics	Symbol	Min	Typ	Max	Unit
Supply Voltage	VDDA - VSSA VDDD - VSSD	3.15	3.3	3.45	V
Supply Voltage Difference	VDDA - VDDD	-0.1	0.0	0.1	V
Reference Input Voltage(Externally)	REFTOP REFBOT	– –	1.9 1.4	– –	V
Analog Input Voltage (+)	AINT	1.4	–	1.9	V
Analog Input Voltage (-)	AINC	1.9	–	1.4	V
Operating Temperature	Topr	0	–	70	°C

NOTE: It is strongly recommended that all the supply pins (VDDA, VDDD) be powered from the same source to avoid power latch-up.

DC ELECTRICAL CHARACTERISTICS

| Characteristics	Symbol	Min	Typ	Max	Unit	Conditions
Resolution	–	–	–	10	Bits	–
Reference Current	IREF	–	2	3	mA	
Differential Linearity Error	DLE	–	–	±1.0	LSB	AINT: 0.2 ~ 1.2V (Ramp Input)
Integral Linearity Error	ILE	–	–	±2.0	LSB	Fck: 1MHz
Bottom Offset Voltage Error	EOB	–	–	20	LSB	
Top Offset Voltage Error	EOT	–	–	20	LSB	

NOTES:
1. Converter Specifications (unless otherwise specified)
   VDDA=3.3V   VDDD=3.3V
   VSSA=GND   VSSD=GND
   Ta=25°C
2. TBD: To Be Determined

AC ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Min	Typ	Max	Unit	Conditions
Maximum Conversion Rate	fc	30	–	–	MSPS	AINT: 1MHz Sine Signal (source resolution > 12-bit)
Dynamic Supply Current	Ivdd	–	25	30	mA	fc = 30MHz (without system load)
Signal - to - Noise Ratio	SNR	48	52	54	dB	AINT = 1MHz fc = 30MHz

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TIMING DIAGRAM (MAIN FUNCTION)
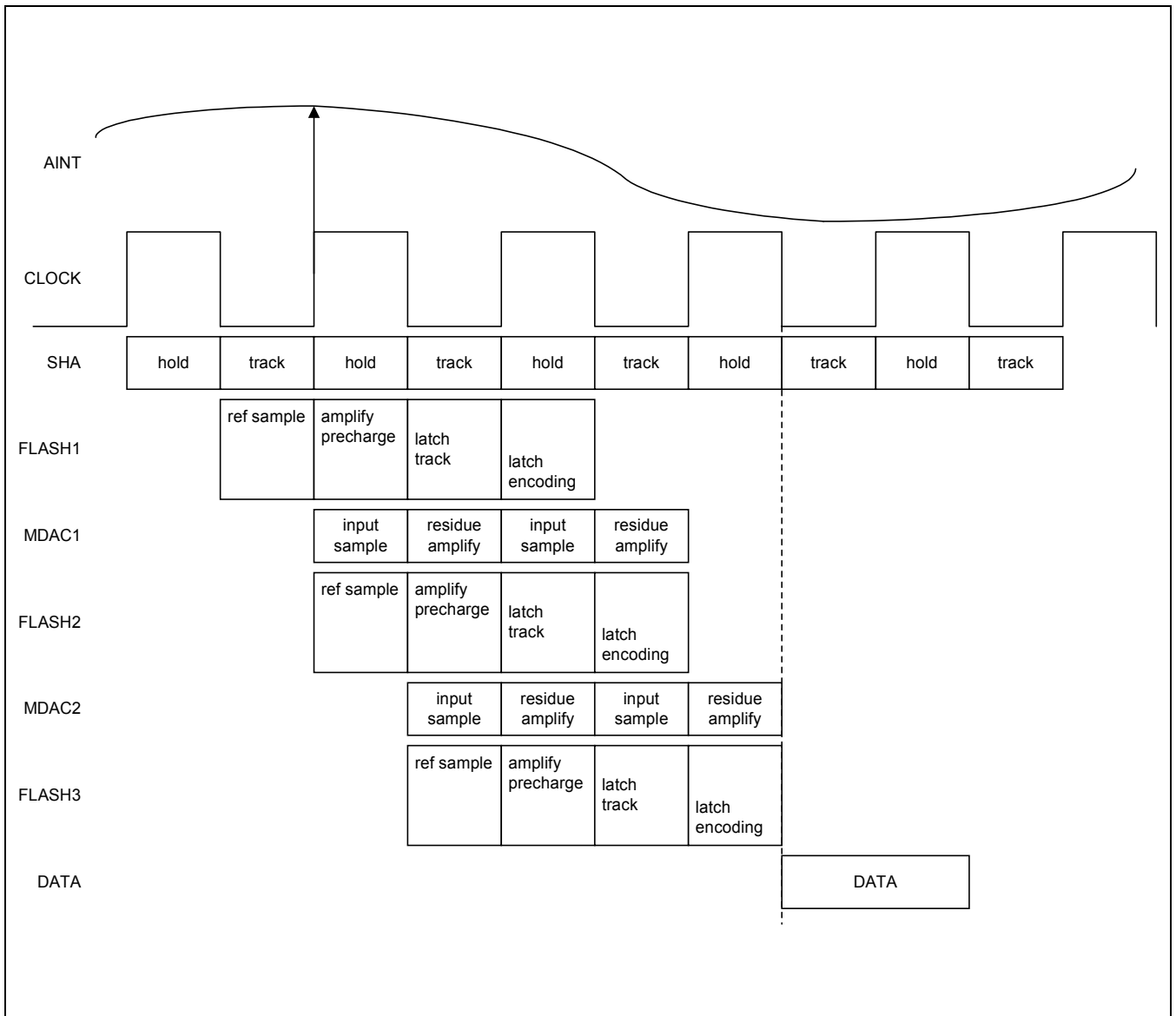
FUNCTIONAL DESCRIPTION

1. bw1217x is a three step A/D Converter comprising three 4-bit flash ADC and two multiplying DAC. The N-bit flash ADC is composed of $2^{(n-1)}$ latching comparators, and multiplying DAC is composed of $2*(N+2)$ capacitors and two fully-differential amplifier.

2. bw1217x operates as follows. During the first "L" cycle of external clock the analog input data is tracked and sampled, and the input is held from the rising edge of the external clock, which is fed to the first 4-bit flash ADC, and the first multiplying DAC. Multiplying DAC reconstructs a voltage corresponding to the first 4-bit ADC's output, and finally amplifies a residue voltage by 2^3. The second 4-bit flash ADC, and MDAC are worked as same manner, finally amplifiers a residue voltage, which is the difference between first MDAC's output and reconstructed voltage by 2^2. The third 4-bit flash ADC, and MDAC are worked as previous stages.

3. bw1217x has the error correction scheme, which handles the output from mismatch in the first, second and third flash ADC.

MAIN BLOCK DESCRIPTION

1. SAH

    SAH(track and hold) is the circuit that samples the analog input signal and holds that value until next sample-time. It is good as small as its different value between analog input signal and output signal. SAH amp gain must be higher than 66dB at least for less than 1/2LSB of SAH error voltage at 10bit ADC and its conversion frequency is 30MHz, its settling-time must be shorten than 12ns. This SAH is consist of fully differential op amp, switching tr. and sampling capacitor. The sampling clock are non-overlapping clocks(Q1,Q2) and sampling capacitor value is 1.2pF. SAH uses independentbias to protect interruption of any other circuit. SAH amp is designed that open-loop dc gain is higher than 70dB, phase margin is higher than 60degree. Its input block is designed to be the rail-to-rail architecture using complementary differential pair.

2. FLASH

    The 4-bit flash converter compares analog signal(SAH output) with reference voltage, and that result transfers to MDAC and digital correction logic block. It is realized fully differential comparators of 15EA. Considering self-offset, dynamic feed through error, it should distinguish 40mV at least. First, the comparators charge the reference voltage at the sampling capacitors before transferred SAH output. Q2 works this process and Q1 discharges this sampling capacitors. That is, the comparators compare relative different values dual input voltage with dual reference voltage. Its output during Q1 operation is stored at the pre-latch block by Q1P.
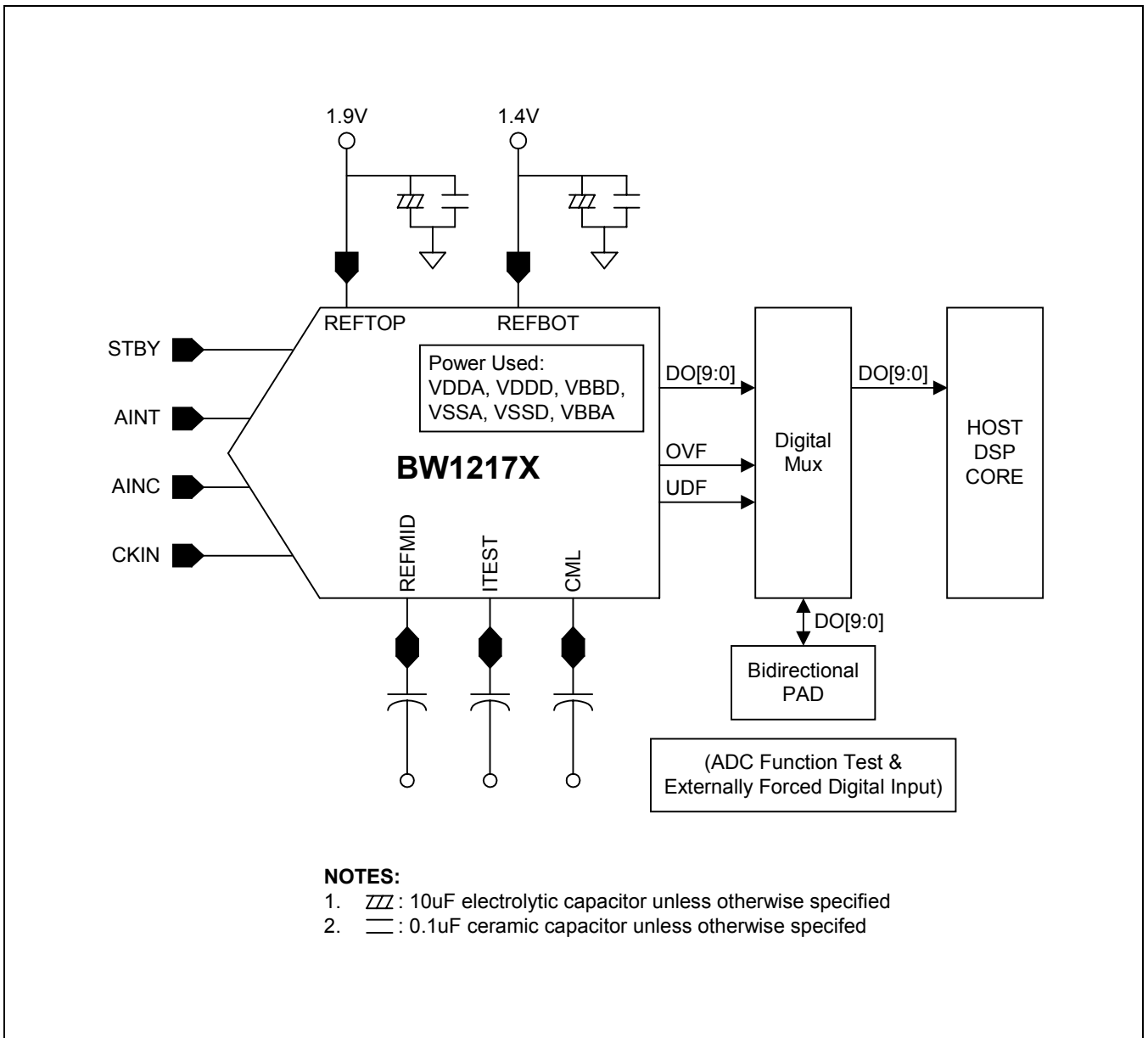
3. MDAC

    MDAC is the most important block at this ADC and it decides the characteristics. MDAC is consist of amp1,amp2, selection logic and capacitor array(c_array). C_array's compositions are the capacitors to charge the analog input and the reference voltage, Switches to control the path. Selection logic controls the c_array internal switches. If Q1 is high, selection's output is all low, the switches of tsw1 are off, the switches of tsw2 are all on. Therefore the capacitors of c_array charges analog input values held at SAH. If Q2 is high, it is reversed and final MDAC output voltage is described the following equation.

    Vout = (AIN - Vref)*8-Vref/2
           AIN=AINT-1.5V

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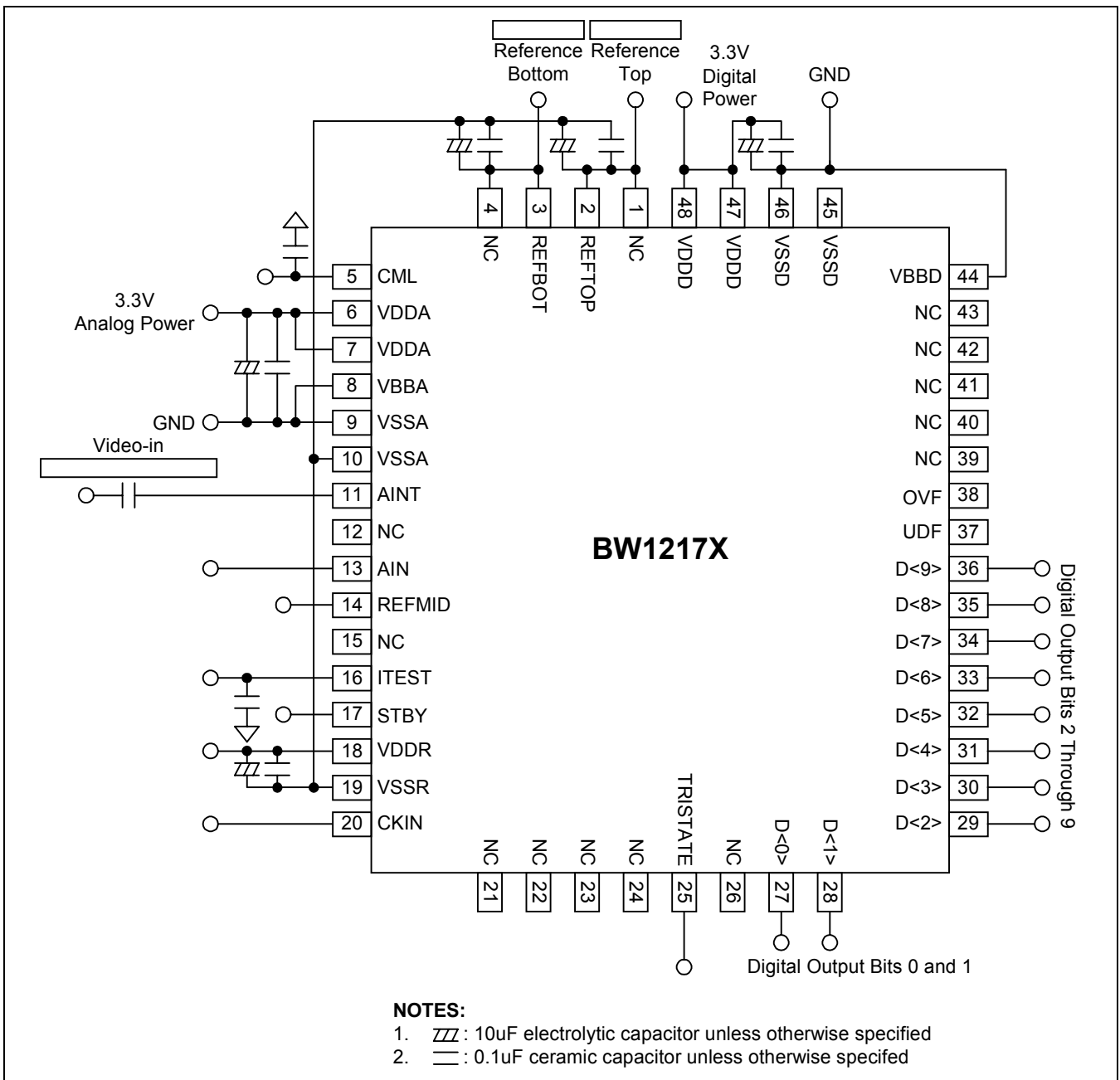
CORE EVALUATION GUIDE

1. ADC function is evaluated by external check on the bidirectional pads connected to input nodes of HOST DSP back-end circuit.

2. The reference voltages may be biased internally through resistor divider.

NOTES:
1. ⚡ : 10uF electrolytic capacitor unless otherwise specified
2. ⎓ : 0.1uF ceramic capacitor unless otherwise specifed

PACKAGE CONFIGURATION

NOTES

1. You can test ADC function by checking external bidirectional pad connected to internal signal path.
2. ESD (Electro Static Discharge) sensitive device. Although the digital control inputs are diode protected, permanent damage may occur on devices subjected to high electrostatic discharges. It is recommended that unused devices be stored in conductive foam or shunts to avoid performance degradation or loss of functionality. The protective foam should be discharged to the destination socket before devices are inserted.
3. NC denotes "No Connection".

NOTES:
1. ⊿⊿⊿ : 10uF electrolytic capacitor unless otherwise specified
2. ⎓ : 0.1uF ceramic capacitor unless otherwise specifed

PACKAGE PIN DESCRIPTION

Name	Pin No.	I/O Type	Pin Description
REFTOP	2	AI	External Reference Top Bias.(1.9V)
REFBOT	3	AI	External Reference Bottom Bias.(1.4V)
CML	5	AB	Internal Bias Point (Test Pin)
VDDA	6,7	AP	3.3V Analog Power
VBBA	8	AG	Analog Sub Bias
VSSA	9,10	AG	Analog Ground
AINT	11	AI	Analog Input (+) Input Range: 1.4~1.9V
AINC	13	AI	Analog Input. (-) Input Range: 1.9~1.4V
REFMID	14	AB	Reference Mid Point (Test Pin)
ITEST	16	AB	open=use internal bias point
STBY	17	DI	High = power saving standby mode (normally gnd)
VDDR	18	PP	Ouput Driver Power (3.3V)
VSSR	19	PG	Output Driver Ground
CKIN	20	DI	Sampling Clock Input
TRISTATE	25	DI	high = high impedance digital output (normally gnd)
DO[9:0]	27~36	DO	Digital Output
UDF	37	DO	Underflow
OVF	38	DO	Overflow
VBBD	44	DG	Digital Substrate Bias
VSSD	45,46	DG	Digital Ground
VDDD	47,48	DP	Digital Power(3.3V)

NOTE: I/O TYPE PP and PG denote PAD Power and PAD Ground respectively.

USER GUIDE

1. Resolution Control.

— Modular structure is the most important feature of bw1217x.

— You can get any resolution you want by combining each primary module (MDAC + FLASH) without major circuit change.

— It means you don't have to redesign the most difficult analog block for another resolution.

— But this simple resolution control method has a limit up to 10bits, otherwise the internal op-amp must be redesigned.
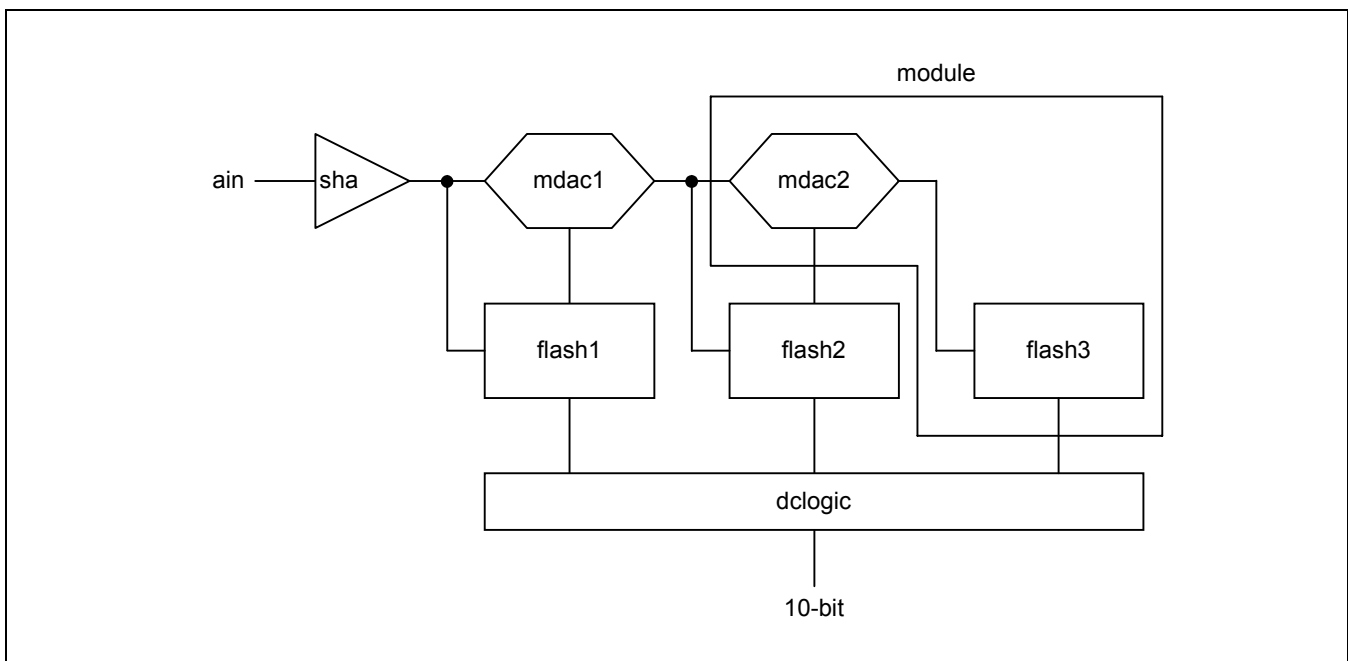
2. Speed Up

— The initial target speed of bw1217x was 30MHz, but it proved to operate well at 35MHz or more   due to a lot of design margin.

3. Input Range Variation.

— The default of the input of this ADC is differential -0.5V ~ +0.5V.

— The bias voltages of both AINT and AINC are 0.2V~1.2V, and their offset is 0.7V.

— In order to change to another input voltage range, alter the voltage values of AINT and AINC after setting Reftop and Refbot to the maximum value of input range.

— If you want single ended input, fix AINC to 0.7V as a ground and the internal input voltage level is V(aint)-0.7V.

4. Verilog Modeling

— Verilog modeling needs 64bits for only one analog real signal.

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FEEDBACK REQUEST

It should be quite helpful to our ADC core development if you specify your system requirements on ADC in the following characteristic cheking table and fill out the additional questions.

We appreciate your interest in our products. Thank you very much.

Characteristic	Min	Typ	Max	Unit	Remarks
Analog Power Supply Voltage				V	
Digital Power Supply Voltage				V	
Bit Resolution				Bit	
Reference Input Voltage				V	
Analog Input Voltage				Vpp	
Operating Temperature				°C	
Integral Non-linearity Error				LSB	
Differential Non-linearity Error				LSB	
Bottom Offset Voltage Error				mV	
Top Offset Voltage Error				mV	
Maximum Conversion Rate				MSPS	
Dynamic Supply Current				mA	
Power Dissipation				mW	
Signal-to-noise Ratio				dB	
Pipeline Delay				CLK	
Digital Output Format (Provide detailed description & timing diagram)					

1. Between single input-output and differential input-output configurations, which one is suitable for your system and why?

2. Please comment on the internal/external pin configurations you want our ADC to have, if you have any reason to prefer some type of configuration.

3. Freely list those functions you want to be implemented in our ADC, if you have any.

NOTES